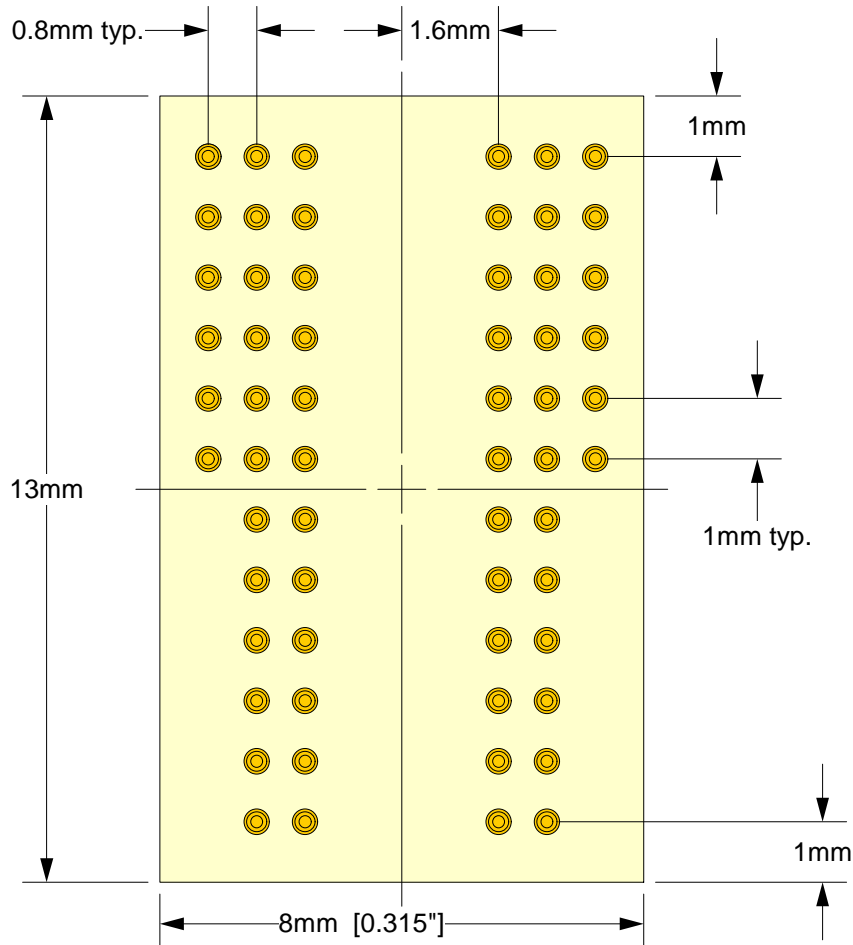
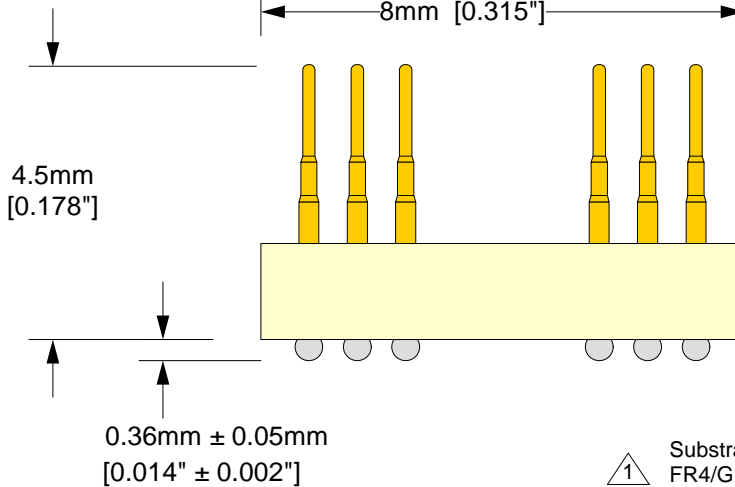


Top View



Side View



- 1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material; Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: Giga-snaP BGA SMT Foot

60 position terminal pins (0.8mm x 1.0 mm centers, 6x12 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA60G-B-61F Drawing	Status: Released	Scale: 8:1	Rev: B
<p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: A. Evans		Date: 06/01/09
	File: SF-BGA60G-B-61F Dwg.mcd		Modified: 08/29/14